

# **SUD493Z**

## **Small Signal Fast Switching Diode**

#### **General Description**

General-purpose switching diodes, fabricated in planar technology, and packaged in small SOT-343 surface mounted device (SMD) packages.

#### **Features and Benefits**

- Silicon epitaxial planar diode
- High switching speed: trr≤4ns
- · Low forward drop voltage and low leakage current
- "Green" device and RoHS compliant device
- Available in full lead (Pb)-free device







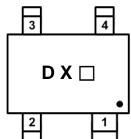
#### **Applications**

· Ultra high speed switching application

#### **Ordering Information**

| Part Number | Marking Code | Package | Packaging   |
|-------------|--------------|---------|-------------|
| SUD493Z     | DX 🗆         | SOT-343 | Tape & Reel |

### **Marking Information**



D X = Specific Device Code

☐ = Year & Week Code Marking

#### **Pinning Information**

| Pin | Description       | Simplified Outline | Graphic Symbol |
|-----|-------------------|--------------------|----------------|
| 1   | Anode (Diode 1)   | 3 4                | 3 4            |
| 2   | Anode (Diode 2)   |                    |                |
| 3   | Cathode (Diode 2) |                    | <b>1</b>       |
| 4   | Cathode (Diode 1) | 2 1                |                |

#### **Absolute Maximum Ratings** (T<sub>amb</sub>=25°C, Unless otherwise specified)

| Characteristic                                    | Symbol           | Ratings | Unit |
|---|------------------|---------|------|
| Maximum repetitive peak reverse voltage           | $V_{RM}$         | 85      | V    |
| Continuous reverse voltage                        | V <sub>R</sub>   | 80      | V    |
| Maximum average forward rectified current         | Io               | 100     | mA   |
| Forward current (DC)                              | I <sub>F</sub>   | 100     | mA   |
| Maximum repetitive peak forward current           | I <sub>FM</sub>  | 300     | mA   |
| Non-repetitive peak forward surge current(t=10ms) | I <sub>FSM</sub> | 2       | Α    |
| Power dissipation 1)                              | P <sub>D</sub>   | 150     | mW   |

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

# Thermal Characteristics ( $T_{amb}$ =25°C, Unless otherwise specified)

| Characteristic                             | Symbol               | Ratings   | Unit |
|--|----------------------|-----------|------|
| Thermal resistance, junction to ambient 1) | $R_{\text{th(j-a)}}$ | 830       | °C/W |
| Operating junction temperature             | Tj                   | 150       | °C   |
| Storage temperature range                  | T <sub>stg</sub>     | -55 ~ 150 | °C   |

<sup>1)</sup> Device mounted on FR-4 board with recommended pad layout.

# Electrical Characteristics (T<sub>amb</sub>=25°C, Unless otherwise specified)

| Characteristic                | Symbol            | Test Condition                | Min. | Тур. | Max. | Unit |
|-------------------------------|-------------------|-------------------------------|------|------|------|------|
| Forward voltage <sup>2)</sup> | V <sub>F(1)</sub> | I <sub>F</sub> =1mA           | -    | 0.6  |      | V    |
|                               | $V_{F(2)}$        | I <sub>F</sub> =10mA          | ı    | 0.7  | ı    | V    |
|                               | $V_{F(3)}$        | I <sub>F</sub> =100mA         | -    | 0.9  | 1.2  | V    |
| Reverse leakage current 3)    | I <sub>R</sub>    | V <sub>R</sub> =80V           | -    | -    | 0.5  | uA   |
| Total capacitance             | $C_{T}$           | V <sub>R</sub> =0V, f=1 MHz   | ı    | 2.2  | 4.0  | pF   |
| Reverse recovery time         | t <sub>rr</sub>   | I <sub>F</sub> =10mA (Fig. 5) | -    | 1.6  | 4.0  | ns   |

<sup>&</sup>lt;sup>2)</sup> Pulse test: t<sub>P</sub>≤380 µs, Duty cycle≤2%

<sup>&</sup>lt;sup>3)</sup> Pulse test:  $t_P \le 5 \text{ ms}$ , Duty cycle  $\le 2\%$ 

#### **Rating and Characteristic Curves**

Fig. 1) Typical Forward Characteristics

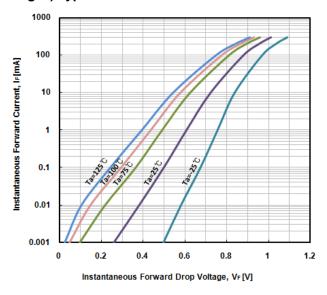


Fig. 2) Typical Reverse Characteristics

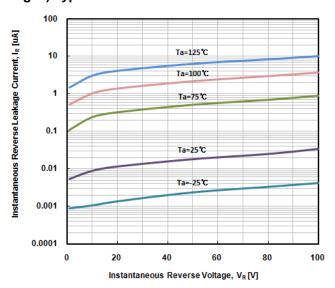


Fig. 3) Typical Total Capacitance Characteristics

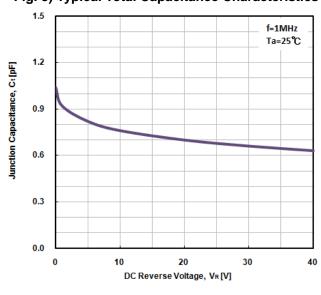


Fig. 4) Reverse Recovery Time vs. Forward Current

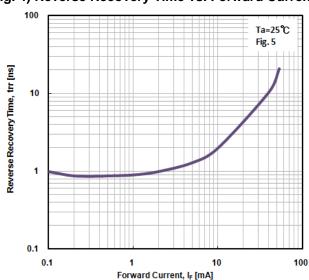
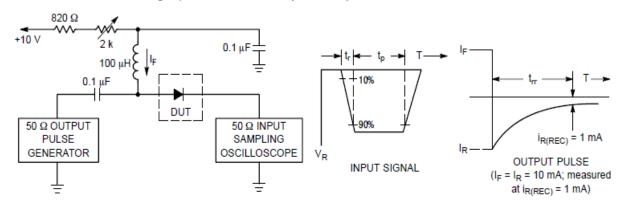
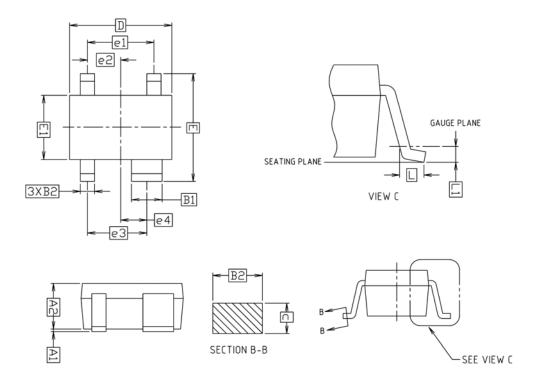


Fig. 5) Reverse recovery time equivalent test circuit

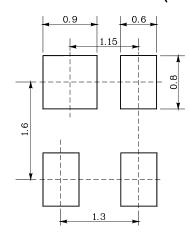


# **Package Outline Dimensions**



|        | MILLIMETERS |         |         | NOTE |
|--------|-------------|---------|---------|------|
| SYMBOL | MINIMUM     | NOMINAL | MAXIMUM | NOIL |
| A1     | 0.00        | _       | 0.10    |      |
| A2     | 0.90        | 0.95    | 1.00    |      |
| B1     | 0.55        | _       | 0.70    |      |
| B2     | 0.25        | _       | 0.40    |      |
| С      | 0.10        | _       | 0.25    |      |
| D      | 1.90        | 2.00    | 2.10    |      |
| Ε      | 1.95        | 2.10    | 2.25    |      |
| E1     | 1.15        | 1.25    | 1.35    |      |
| e1     | 1.30 BSC    |         |         |      |
| e2     | 0.65 BSC    |         |         |      |
| e3     | 1.15 BSC    |         |         |      |
| e4     | 0.50 BSC    |         |         |      |
| L      | 0.25        | -       | _       |      |
| L1     | 0.15 BSC    |         |         |      |

#### **X** Recommend PCB solder land (Unit: mm)



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